

AMENDMENTS TO THE CLAIMS

The current status of all claims in the Application is as follows:

1. (CURRENTLY AMENDED) A coil bobbin comprising:  
a housing having a floor with at least one electrical lead-in projecting therethrough for attachment to a printed circuit board, said at least one electrical lead-in being provided with thermal-strain relief formed in said electrical lead-in between said floor and said printed circuit board.
2. (ORIGINAL) The coil bobbin of Claim 1 wherein said thermal-strain relief comprises at least one loop formed in said electrical lead-in.
3. (ORIGINAL) The coil bobbin of Claim 2 wherein said loop comprises a U-shaped portion.
4. (ORIGINAL) The coil bobbin of Claim 2 wherein said loop comprises an O-shaped portion.